Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A circuit board device for an information apparatus comprising:

a base board having mounted thereupon a plurality of low-frequency electronic components; and

a multilayer module board mounted at one surface of the base board and having mounted thereupon a plurality of high-frequency electronic components including at least a CPU and a memory, wherein:

the multilayer module board is one of (i) a low-end module board, (ii) a high-speed module board that operates at higher speed than the low-end module board or (iii) an advanced function module board having more functions than the low-end module board; and

the base board is connected with one of (i) the low-end module board, (ii) the high-speed module board or (iii) the advanced function module board.

Claim 2. (Canceled)

3. (Previously Presented) A navigation system comprising a circuit board device for an information apparatus according to claim 1.

Claim 4. (Canceled)

5. (Previously Presented) The multilayer module board used in the circuit board device for an information apparatus according to claim 1, comprising:

a plurality of high-frequency electronic components including a CPU and a memory mounted at, at least, a surface thereof, wherein:

the plurality of high-frequency electronic components are connected with one another through a wiring patterns formed at an inner layer thereof.

6. (Previously Presented) The multilayer module board according to claim 5, wherein an overall shape of the multilayer module board is rectangular and the multilayer module board comprises connector terminals provided as separate members each soldered onto one of four peripheral edges thereof.

7. (Previously Presented) The multilayer module board according to claim 6, wherein:

the four connector terminals each include a narrow, elongated base portion constituted of resin and a plurality of pins fixed to the base portion; and

the four connector terminals are each carried with the base portion attached to a transfer adapter and the four connector terminals are connected through soldering onto a rear surface of the board while attached to the transfer adapter.

8. (Currently Amended) The multilayer module board according to claim 6, wherein:

the four connector terminals each include [[;]]

a narrow, elongated base portion constituted of resin;

a plurality of pins fixed to the base portion;

aligning pins projecting at both ends of the base portion to be used when soldering the connector terminal onto a rear surface of the board; and

inclined surfaces for position control formed at both ends of the base portion to be used when soldering the connector terminal;

a pair of positioning holes at which the aligning pins are loosely fitted are formed at each of four corners of the board; and

positions of the connector terminals are controlled when soldering the connector terminals as the inclined surfaces for position control at adjacent

connector terminals come into contact with each other while the aligning pins are loosely fitted at the positioning holes.

9. (Previously Presented) A multilayer module board comprising:

a plurality of high-frequency electronic components including a CPU and a memory mounted at, at least, a surface thereof, wherein:

the plurality of high-frequency electronic components are connected with one another through a wiring pattern formed at an inner layer thereof;

an overall shape of the multilayer module board is rectangular and the multilayer module board comprises connector terminals provided as separate members each soldered onto one of four peripheral edges thereof;

the four connector terminals each include a narrow, elongated base portion constituted of resin and a plurality of pins fixed to the base portion; and

after the four connector terminals are each carried with the base portion attached to a transfer adapter, the four connector terminals are connected through soldering onto a rear surface of the board while attached to the transfer adapter.

10. (Currently Amended) A multilayer module board comprising:

a plurality of high-frequency electronic components including a CPU and a memory mounted at, at least, one surface thereof, wherein:

the plurality of high-frequency electronic components are connected with one another through a wiring pattern formed at an inner layer thereof;

an overall shape of the multilayer module board is rectangular and the multilayer module board comprises connector terminals provided as separate members each soldered onto one of four peripheral edges thereof;

the four connector terminals each include [[;]]

a narrow, elongated base portion constituted of resin;

a plurality of pins fixed to the base portion;

aligning pins projecting at both ends of the base portion to be used when soldering the connector terminal onto a rear surface of the board; and

inclined surfaces for position control formed at both ends of the base portion to be used when soldering the connector terminal;

a pair of positioning holes at which the aligning pins are loosely fitted are formed at each of four corners of the board; and

positions of the connector terminals are controlled when soldering the connector terminals as the inclined surfaces for position control at adjacent connector terminals come into contact with each other while the positioning pins are loosely fitted at the positioning holes.

Claims 11.-14. (Canceled)